



Material Content Data Sheet



Sales Product Name		TLE5009 E2000		Issued		20. July 2018		
MA#		MA000983860						
Package		PG-DSO-8-16		Weight*		83.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.725	2.07	2.07	20743	20743
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.717	0.86		8622	
wire	non noble metal	copper	7440-50-8	29.121	35.01	35.92	350078	359239
	noble metal	gold	7440-57-5	0.211	0.25	0.25	2539	2539
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1174
encapsulation	plastics	epoxy resin	-	4.492	5.40		53999	
	inorganic material	silicondioxide	60676-86-0	44.235	53.19	58.71	531768	586941
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9784	9784
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7817	7817
glue	plastics	acrylic resin	-	0.237	0.28		2846	
	noble metal	silver	7440-22-4	0.839	1.01	1.29	10091	12937
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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